

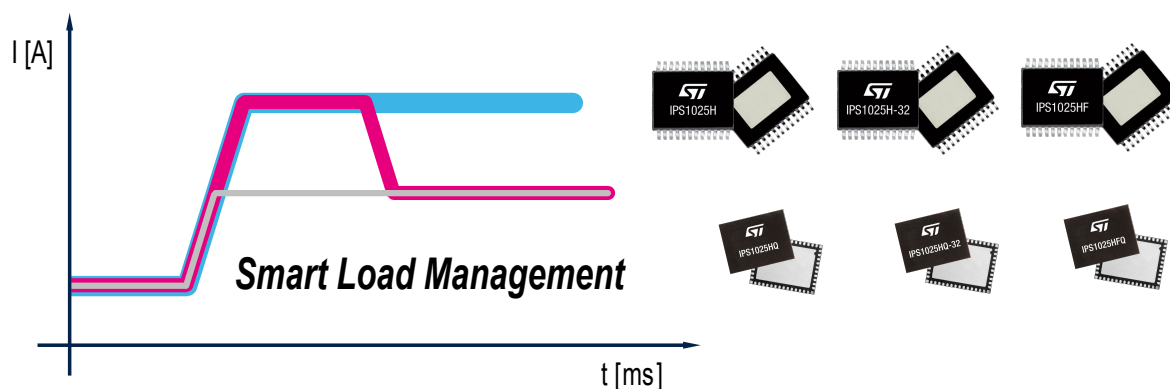
Understanding the Smart Load Management for IPS1025 family



Abstract

This document introduces the new ST devices IPS1025H, IPS1025H-32 and IPS1025HF (as well as the equivalent QFN48L 8x6 mm package options IPS1025HQ, IPS1025HQ-32 and IPS1025HFQ) and focuses, with a practical example, on their market-unique *Smart Load Management* feature.

Driving efficiently the wide set of industrial loads with diverse electrical parameters by a single chip is a typical challenge in industrial digital I/O applications: the Smart Load Management responds to this requirement.



1 Introduction

Industrial digital I/O ICs are used in electronic control systems accompanying our everyday life. While they typically drive automation tasks in smart factories and home & building automation, there are also wide application domains in transportation industries and even city & traffic infrastructure control.

Actuators in automation are endpoint, field-layer components allowing the control system to execute electrical and electro-mechanical actions based on information and data received from smart sensors. In general, an actuator can be seen as an electrical load with an impedance of certain character and parameters (resistance, capacitance, inductance). Industrial digital output modules, which drive actuators, therefore need to operate with any actuator installed in the field, regardless of its specific electrical parameters (see [Figure 2](#)).

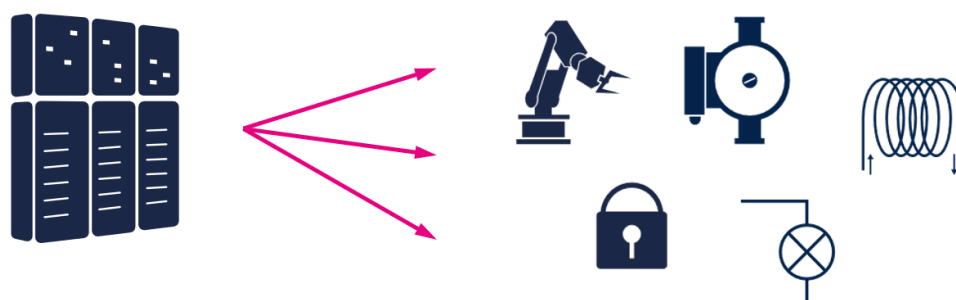
Figure 1. Fields application examples



Figure 2. Variety of industrial actuators

ONE CONTROLLER

**MANY DIFFERENT
ACTUATORS**

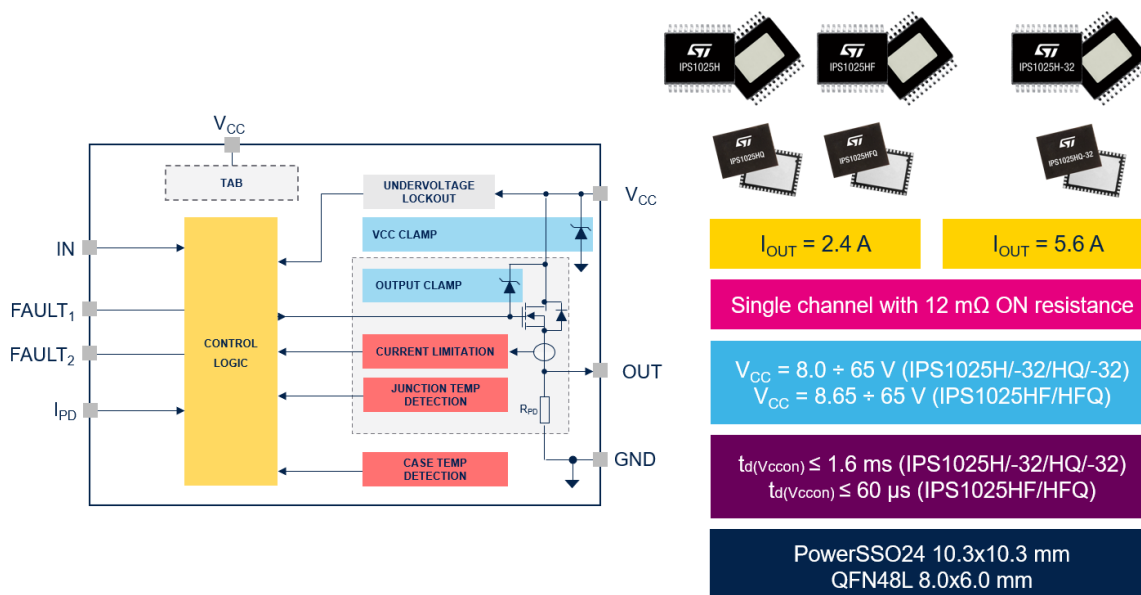


In order to address this technical challenge and to provide design engineers with added flexibility, ST developed a new generation of Intelligent Power Switches (IPS) implementing a unique active current limitation control function called Smart Load Management.

The new ICs IPS1025H, IPS1025H-32 and IPS1025HF (as well as the equivalent QFN48L 8x6 mm package options IPS1025HQ, IPS1025HQ-32 IPS1025HFQ) offer three configurable operation modes for managing current limitation in overload conditions. Whenever turning-on actuators with inrush current (like capacitive loads, or filament lamps) or in the event of failure of an actuator or its wiring (overload, short-circuit), the Smart Load Management comes into action. The following sections explain this feature.

2 IPS1025 family in brief

Figure 3. IPS1025H/HQ, IPS1025H-32/HQ-32 and IPS1025HF/HFQ



The IPS1025 in general represents the new family of single-channel high-side switches with very low on-resistance and an extensive set of protection features securing reliable operation in harsh industrial environments. The three ICs in PowerSSO24 package (IPS1025H, IPS1025H-32 and IPS1025HF) are pin-to-pin compatible as well as the equivalent ones in QFN48L package (IPS1025HQ, IPS1025HQ-32 and IPS1025HFQ), and they are also equivalent in terms of chip architecture and electrical characteristics. The difference lies in the setting of their current limitation levels: IPS1025H/HQ and IPS1025HF/HFQ are suitable for load currents up to 2.4 A, while IPS1025H-32/HQ-32 fits for currents as high as 5.6 A.

Key features

- Selectable output currents
- Extensive protections
- Adjustable inrush current timing
- Short ($\leq 60\text{ }\mu\text{s}$) propagation delay at power-on (IPS1025HF/HFQ)
- Ultra-fast demagnetization of inductive loads
- High switch-OFF energy
- EMC-proof

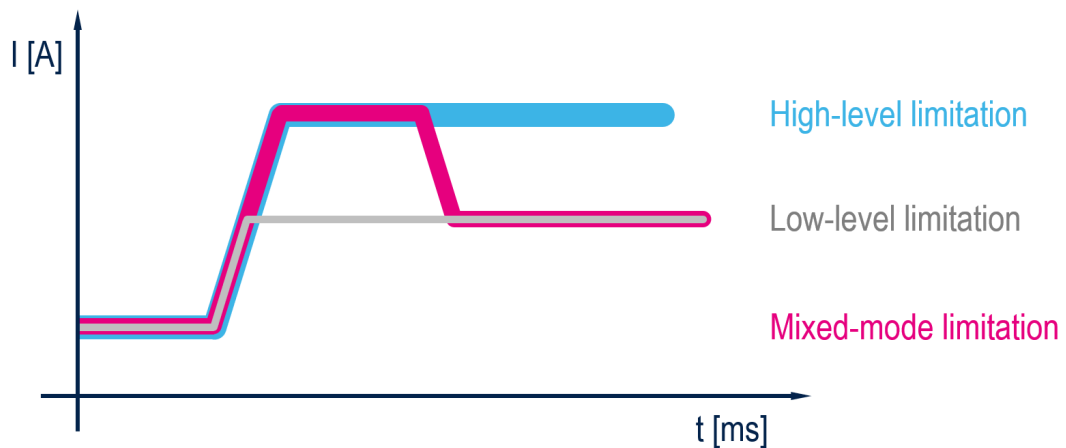
One key important performance indicator of the IPS1025 family is that each IC is fully operational within an extended supply voltage range (up to 60 V). Compliance of all electrical parameters in this range is therefore verified for each chip during its manufacture. An additional safety margin is achieved by the Absolute Maximum Rating set to 65 V. This feature is especially convenient for designing safety-critical applications and systems operating under strong EMC and environmental disturbance, where it helps to significantly reduce product certification efforts, time-to-market and overall development costs.

Moreover, the short propagation delay at power-on ($<60\text{ }\mu\text{s}$) of the IPS1025HF/HFQ make the IC suitable for safety switch applications with redundant architectures addressing higher SIL levels.

3 Smart load management

The IPS1025H/HQ (as well as the IPS1025H-32/HQ-32 and IPS1025HF/HFQ) has three configurable operation modes which determine how the IC behaves in the event of overload. Based on its configuration it can either limit the current at a low value, reducing power dissipation and PCB components stress (low-level limitation, gray line in Figure 4), or it can be set to a higher current limitation level in order to support loads with inrush currents (high-level limitation, blue line in Figure 4). Finally, the third operation mode (Mixed limitation) combines the benefits of both the previous options (magenta line in Figure 4). In this mode, the IC allows to supply its load with an initial current of “high-level” magnitude which it eventually reduces to low-level limitation after a certain time. In order to ensure the true application flexibility, the duration of the initial high-level current supply is adjustable in a range from 100 μ s to 100 ms.

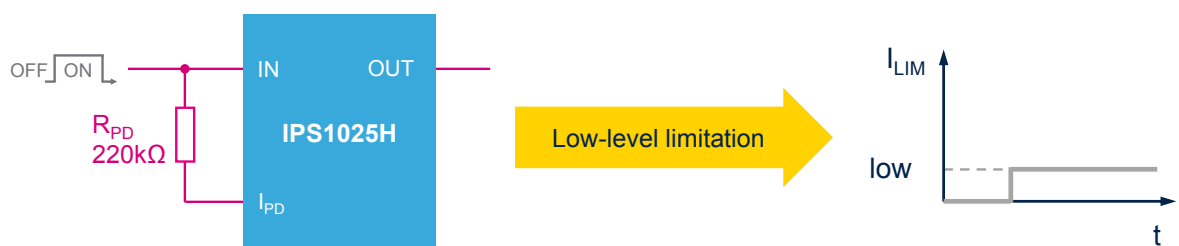
Figure 4. IPS1025H/HQ, IPS1025HF/HFQ and IPS1025H-32/HQ-32



Limitation mode configuration

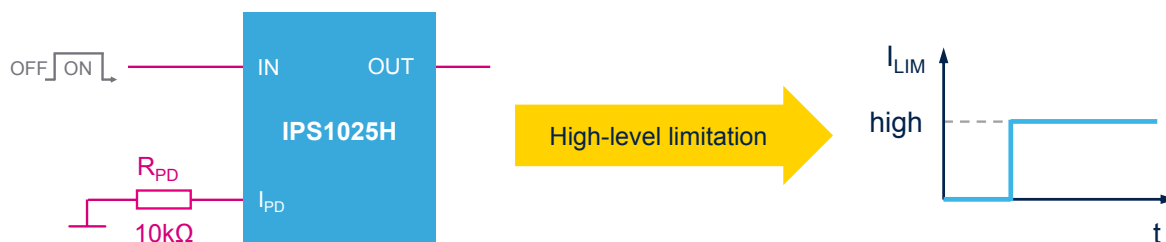
The selection of operation mode is done by a specific connection of pins IN and I_{PD} . Low-level current limitation mode is configured using a resistor R_{PD} connected between IN and I_{PD} (Figure 5).

Figure 5. Low-level limitation mode setting



R_{PD} resistance 220 k Ω is selected to limit the current in full applicable voltage range up to 60 V. Otherwise, a lower value (e.g. 10 k Ω for 24 V applications) can be used.

The second mode (high-level limitation) is set by coupling the I_{PD} pin to GND via an external pull-down resistor (Figure 6).

Figure 6. High-level limitation mode setting


Mixed mode limitation mode is configured by connecting a capacitor instead of pull-down resistor as shown in Figure 7.

Figure 7. Mixed limitation mode setting


Duration of the initial high-level limitation phase (configurable in a range from 100 μ s to 100 ms) is defined by capacitance of C_{PD} as follows:

$$D_{PK}[\mu s] = 215 \times C_{PD}[nF]$$

It is recommended to select the C_{PD} in the following range of capacities in order to maintain precision of the above calculation:

$$470 \text{ pF} \leq C_{PD} \leq 470 \text{ nF}$$

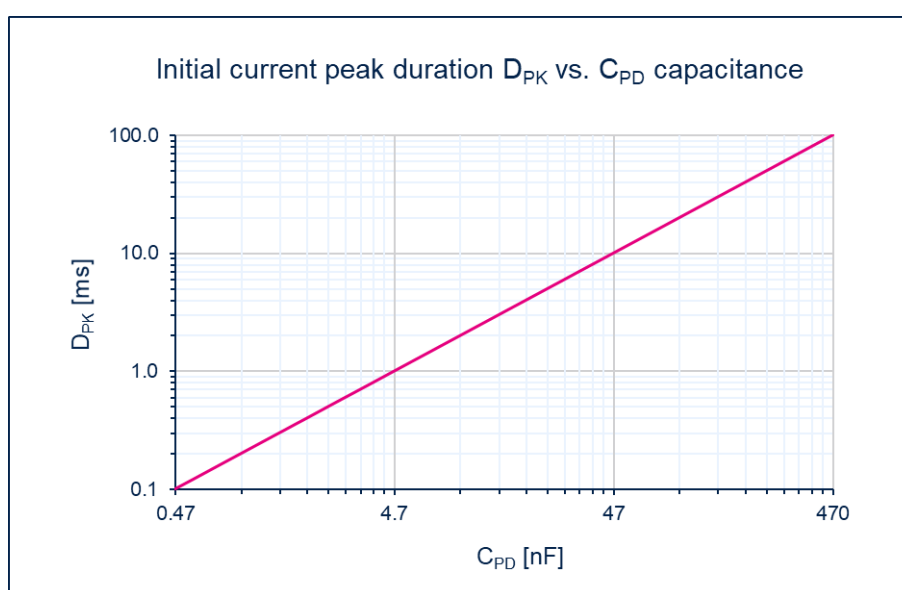
Calculated duration times for most common capacitors are shown in Table 1 and Figure 8.

Table 1. Initial peak duration setting

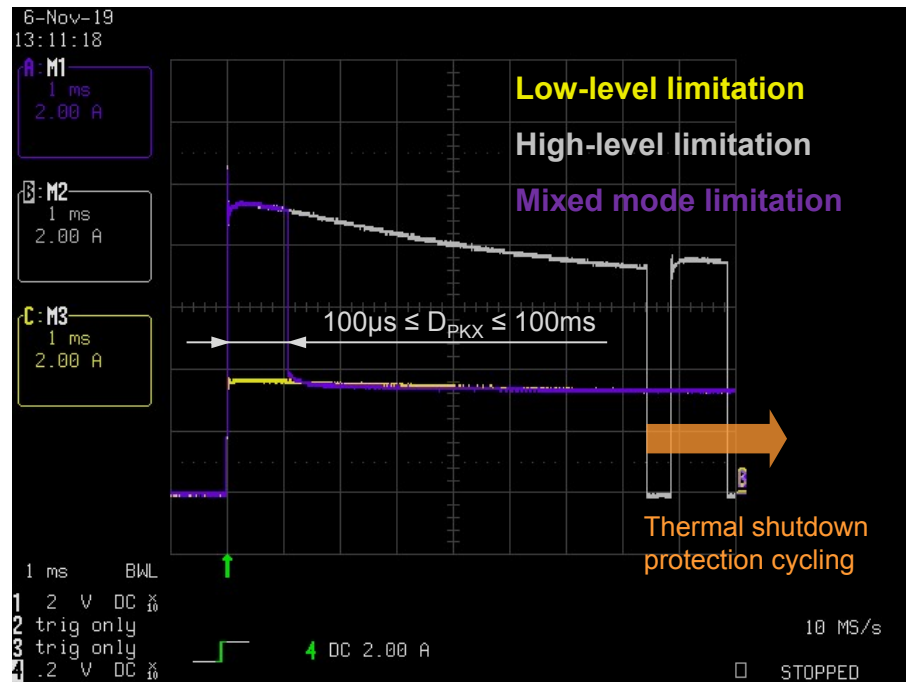
C_{PD} [nF]	D_{PK} [μ s]
0.47	101.1
0.68	146.2
1	215.0
1.5	322.5
2.2	473.0
3.3	709.5

C_{PD} [nF]	D_{PK} [ms]
4.7	1.0
6.8	1.5
10	2.2
15	3.2
22	4.7
33	7.1

C_{PD} [nF]	D_{PK} [ms]
47	10.1
68	14.6
100	21.5
150	32.3
220	47.3
470	101.1

Figure 8. Initial peak duration setting


Comparison of all three current limitation modes in operation is shown on the scope capture in [Figure 9](#).

Figure 9. Comparison of current limitation modes


It is important to note that during active current limitation the integrated power switch operates in linear mode, generating a significant voltage drop V_{DS} . This results in power dissipation proportional to the conducted current I_{LIM} :

$$P_{LIM} = V_{DS} \times I_{LIM}$$

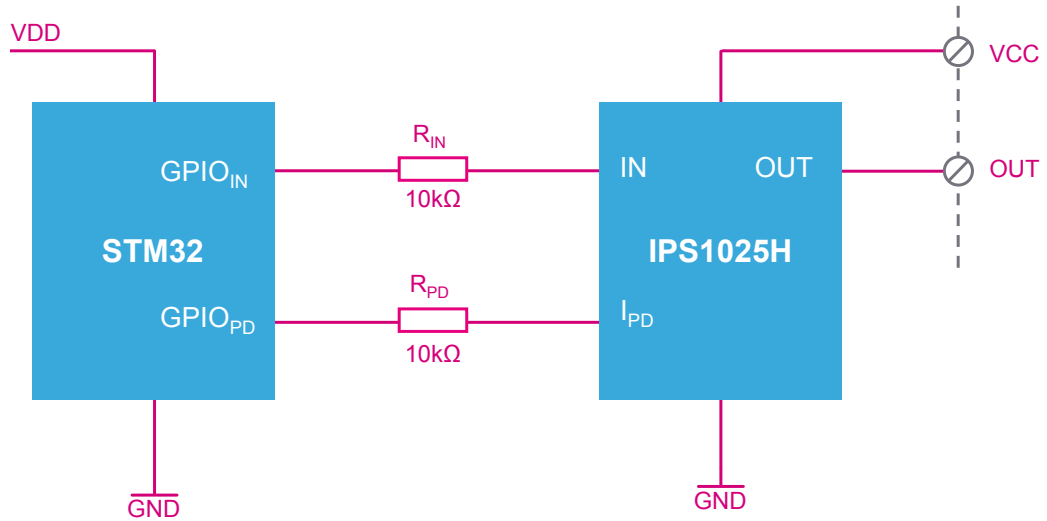
In order to protect the IC and the PCB from overheating, each IC of the IPS1025 family integrates an additional protection mechanism called Two-level thermal shutdown.

This protection operates on a two-level basis protecting the IC output channel and also the temperature of the IC itself. The shutdown effect of this feature is visible in [Figure 9](#) after approximately 7.5 ms with high-level limitation setting (gray waveform).

Dynamic limitation mode control

The previous section described the standard way of configuring the current limitation mode on the system level. There is, however, one additional possibility which brings an additional level of freedom into the digital I/O systems controlling: Dynamic configuration of the current limitation mode.

With this approach, current limitation mode can be configured during application runtime by the host microcontroller. In [Figure 10](#) the output switch of the IC is controlled by two dedicated signals of the host microcontroller (GPIO_{IN} and GPIO_{PD}). This configuration allows to flexibly select between low (GPIO_{PD} = HIGH) and high-level limitation (GPIO_{PD} = LOW) mode based on application conditions.

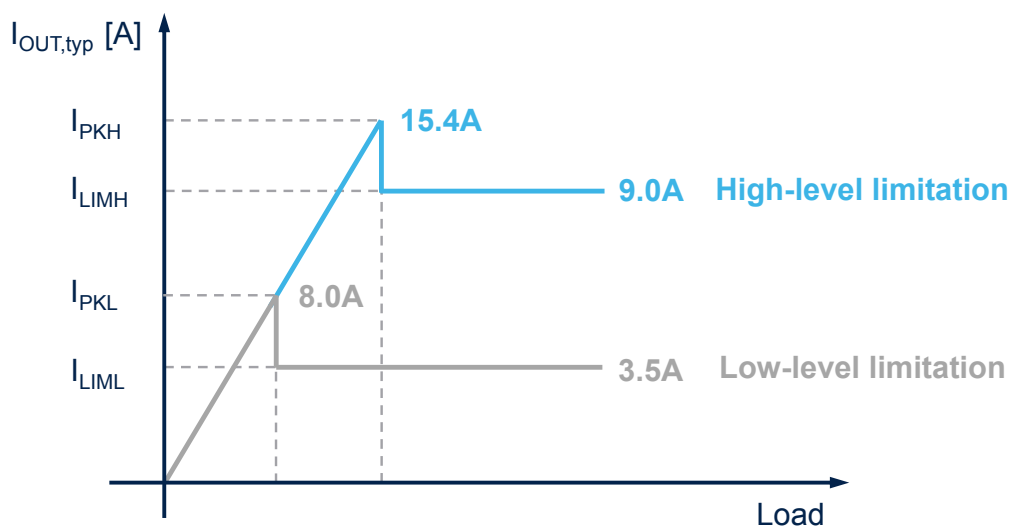
Figure 10. Dynamic configuration of current limitation mode


Understanding datasheet parameters

Although the Smart Load Management function and its configuration is relatively simple, there are several current level parameters that come into play. The overall picture is further complicated by the fact that three IC part numbers are available with two different current limitation levels (IPS1025H/HF or IPS1025HQ/HFQ and the IPS1025H-32/HQ-32 option). The list of related electrical parameters in the datasheet [1] might look slightly exhaustive at first glance so let's clarify the situation using a few simple illustrations.

IPS1025H/HQ and IPS1025HF/HFQ

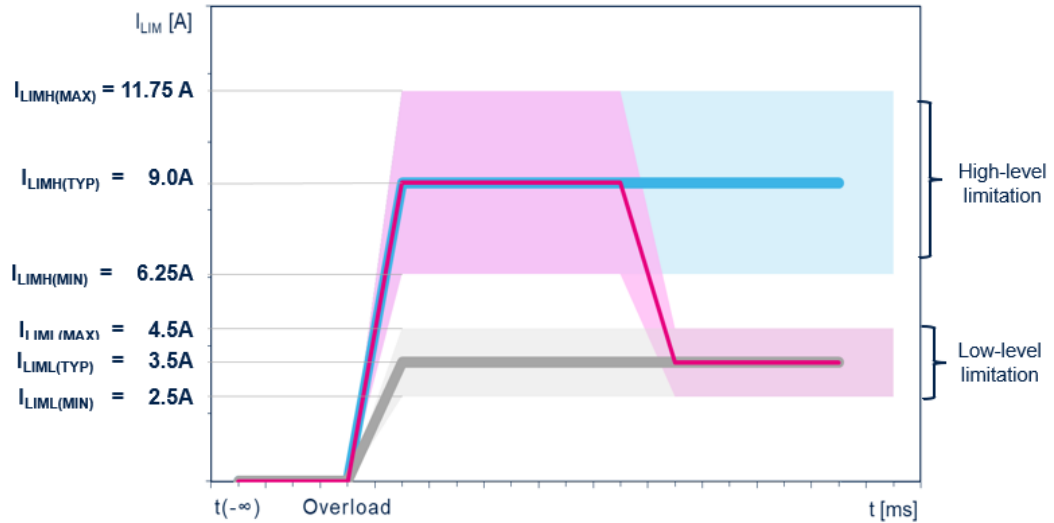
The specification of the IPS1025H/HF (as well as the QFN48L option) was tuned to fit with most 2 A industrial digital output applications in general. Its overall current levels are lower compared to the 'H-32' complement IC. In order to activate the current limitation mechanism a certain triggering threshold is always defined. On the IPS1025H/HF two such thresholds are defined: one for low-level limitation and a second one for high-level limitation, as shown in Figure 11.

Figure 11. Current limitation: activation thresholds (IPS1025H/HQ, IPS1025HF/HFQ) and limitation levels


When the current limitation threshold is exceeded, the power switch starts to limit the current at its specified level according to the selected operation mode. This constant current level is, by principle, lower than the activation peak as is also shown in Figure 11.

Figure 12 shows the current limitation levels for each of the three operation modes. Each line, showing the typical values, is accompanied by the distribution band reflecting the possible spread in IC production process (minimum and maximum values, [1]).

Figure 12. Current limitation levels (IPS1025H/HQ and IPS1025HF/HFQ)



IPS1025H-32/HQ-32

The IPS1025H-32 (as well as the QFN48L option) allows to deliver higher load currents compared to the standard version. This is especially beneficial in applications where we need to temporarily supply currents of higher magnitude (for example when we need to power-up some actuator with significant input capacity in a very short time).

Figure 13. Current limitation: activation thresholds (IPS1025H-32) and limitation levels

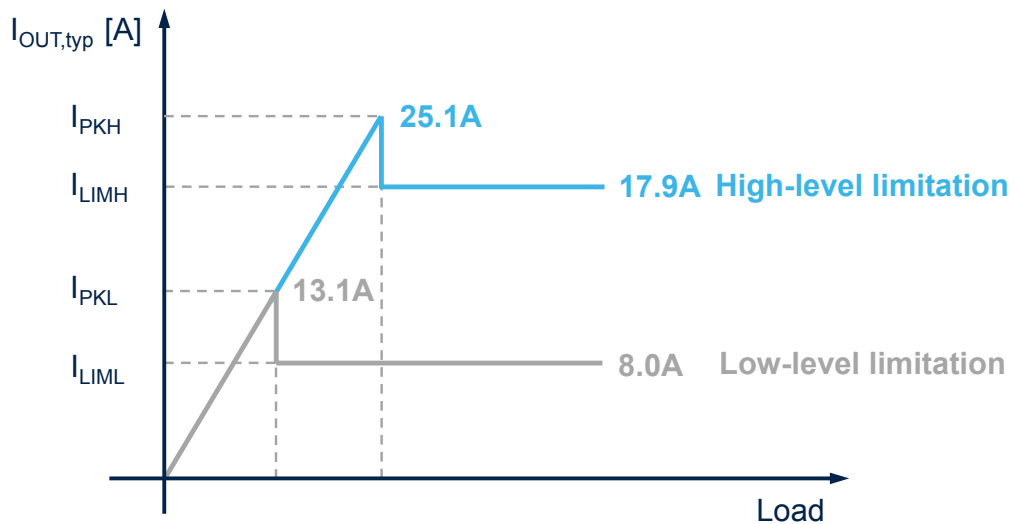
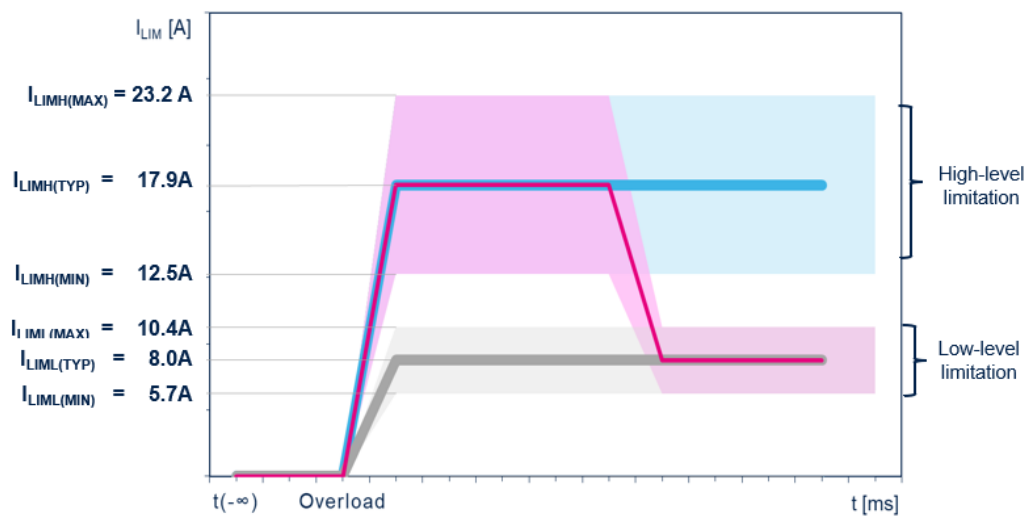


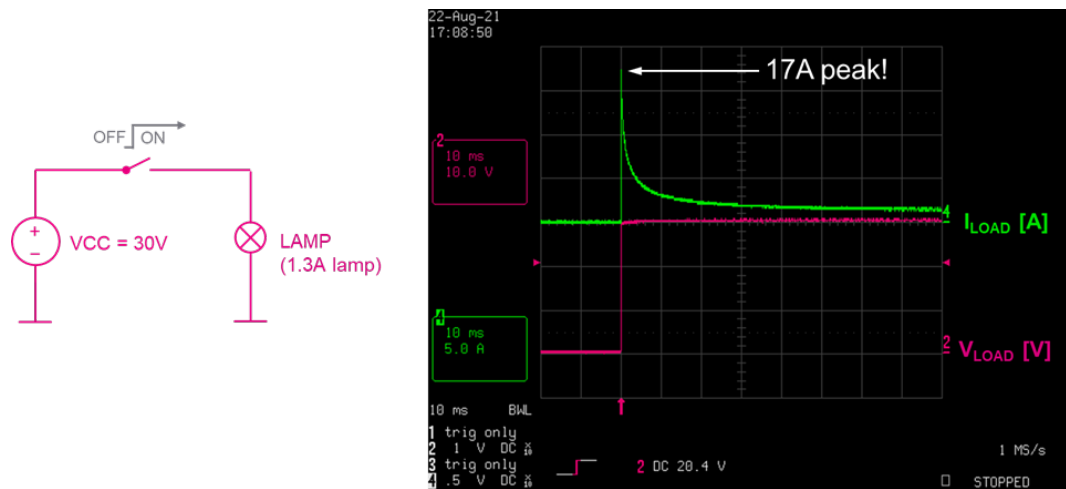
Figure 14. Current limitation levels (IPS1025H-32/HQ-32)


Current limitation activation thresholds and steady-state limit values of the IPS1025H-32/HQ-32 are shown in Figure 13 and Figure 14.

4 Function example: driving filament lamps

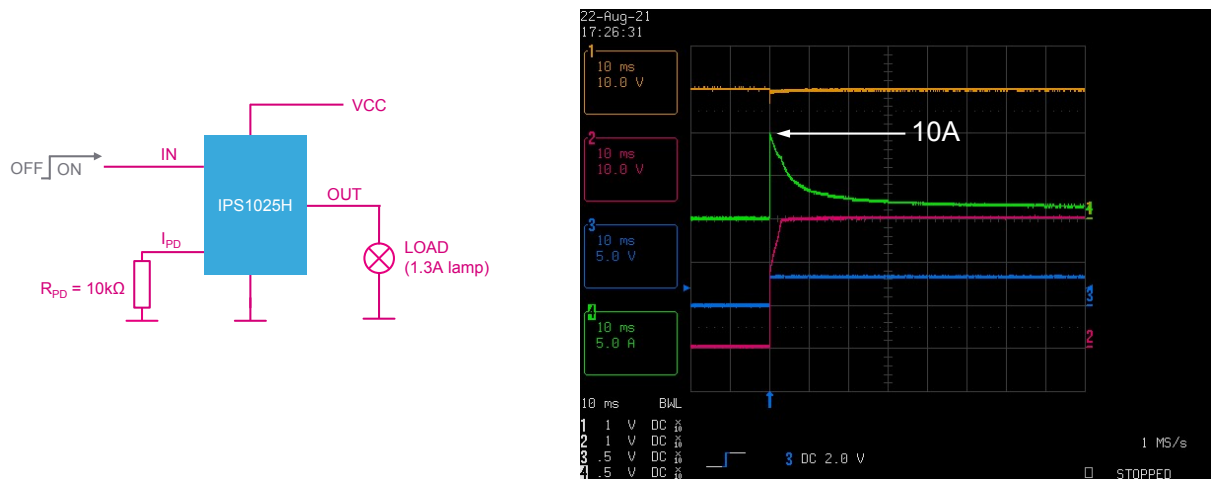
Let's examine the Smart Load Management in practice when driving lamps. A filament lamp can serve as a simple model example since it is characterized by a high current peak at switch-on. This effect is caused by a very low resistance of the filament until it is heated-up.

Figure 15. Cold lamp turn-on



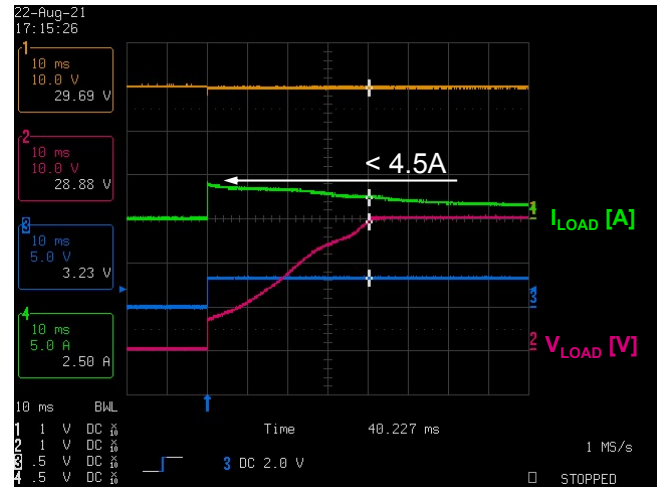
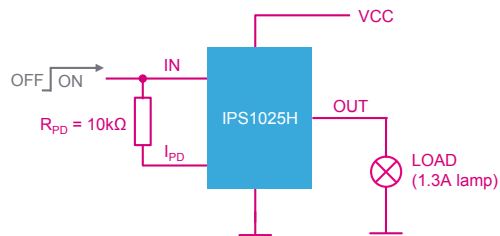
In Figure 15 we see that the initial current transient reaches 17 A during turn-on. Such a peak, if it occurs in a digital I/O system, can overload PCB tracks and components but it might also negatively affect power supply stability or contribute to severe EMC issues in the system.

Figure 16. Current transient reduction using high-level limitation



Using the high-level limitation, we can reduce the amplitude below 10 A while still turning the lamp on in a comparable time (Figure 16). With this approach we can achieve a reasonable trade-off between current transient amplitude and switching dynamics.

However: 10 A might still be too high an over-current for some designs (e.g. dense multichannel I/O modules with tiny connectors). In such cases, we can benefit from the low-level limitation mode. While this approach results in a slightly prolonged heat-up phase, it minimizes current transients and prevents associated EMC issues (Figure 17).

Figure 17. di/dt minimization using low-level limitation


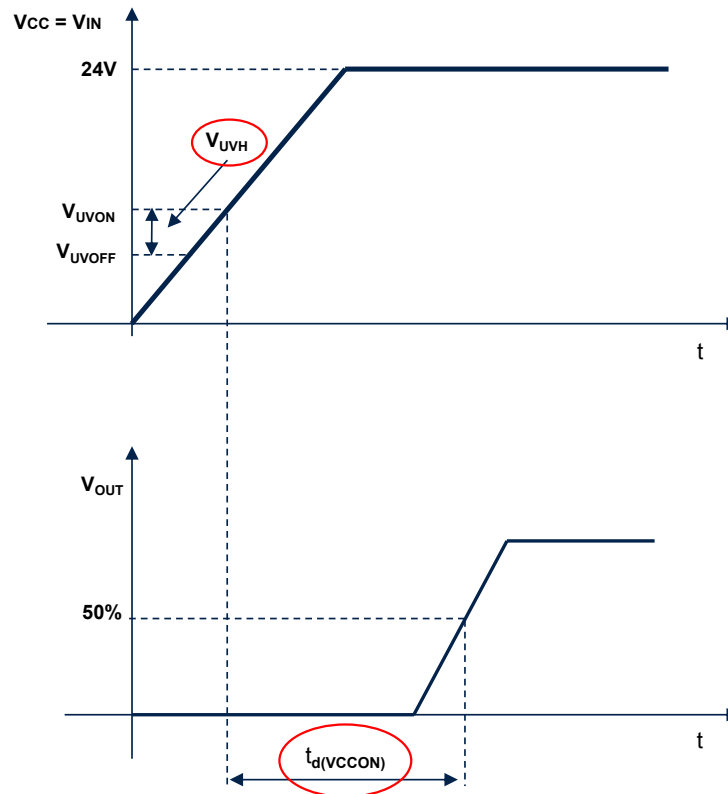
5 IPS1025HF, IPS1025HFQ: main electrical characteristics

The IPS1025HF and IPS1025HFQ are two package options (PowerSSO24 and QFN48L 8x6 mm) of the same design. The electrical characteristics are the same of the IPS1025H and IPS1025HQ, except for three main parameters of the datasheet: V_{UVON} (UVLO activation threshold of the IC), V_{UVH} (UVLO hysteresis of the IC) and $t_d(V_{CCON})$ (input to output propagation delay at power-on).

Table 2. Electrical parameters differing between IPS1025HF/HFQ and IPS1025H/HQ

	IPS1025HF/HFQ	IPS1025H/HQ
$t_d(V_{CCON})$	$\leq 100 \text{ us}$	$\leq 1.6 \text{ ms}$
V_{UVON}	$\leq 8.65 \text{ V}$	$\leq 8.0 \text{ V}$
V_{UVH}	0.95 V	0.5 V

Figure 18. $t_d(V_{CCON})$, V_{UVON} and V_{UVH} parameters meaning



The key parameter of the IPS1025HF/HFQ is the $t_d(V_{CCON})$ guaranteed below 100 μs . This characteristic makes the IC suitable for such safety applications (for example safety switches) with cascaded architecture, for redundancy requirements, and targeting Class 3 classification for interface type C. In fact, interface type C requires response to periodical test pulses and the classification (Class 0, 1, 2 or 3) of the final products depends on the test pulse duration: Class 3 corresponds to the fastest test pulse with duration below 100 μs . In the IPS1025HF/HFQ the $V_{UVON} \leq 8.65 \text{ V}$ is consequence of the wider V_{UVH} than in the IPS1025H/HQ: this is an additional protection against power on with output stage shorted to ground.

Note: for further detail about functional safety aspects, please refer to: ZVEI RECOMMENDATION 2022.01; POSITION PAPER CB 24 I; CLASSIFICATION OF BINARY 24 V INTERFACES; FUNCTIONAL SAFETY ASPECTS COVERED BY DYNAMIC TESTING.

6 Package effects

As previously mentioned, the IPS1025 device family is available in two package options: PowerSSO 24 and QFN48L. The dimensions and the related differences in terms of thermal performances between the two packages are highlighted in this section.

Table 3 shows the values of thermal resistance, evaluated on a Jedec board; the thermal models that the $R_{TH(JA)}$ is calculated from are shown in Figure 19 and Figure 20.

Table 3. IPS1025 family: package dimensions and thermal resistance

Device	Package	$R_{TH(JA)}^{(1)}$
IPS1025H	PowerSSO 24 10.3 X 10.3 mm	22 °C/W
IPS1025H-32	PowerSSO 24 10.3 X 10.3 mm	22 °C/W
IPS1025HF	PowerSSO 24 10.3 X 10.3 mm	22 °C/W
IPS1025HQ	QFN48L 8.0 X 6.0 mm	26 °C/W
IPS1025HQ-32	QFN48L 8.0 X 6.0 mm	26 °C/W
IPS1025HFQ	QFN48L 8.0 X 6.0 mm	26 °C/W

1. Device mounted on a 2s2p Jedec board; values accuracy $\pm 10\%$

Figure 19. IPS1025H/H-32 thermal model on 2s2p Jedec board

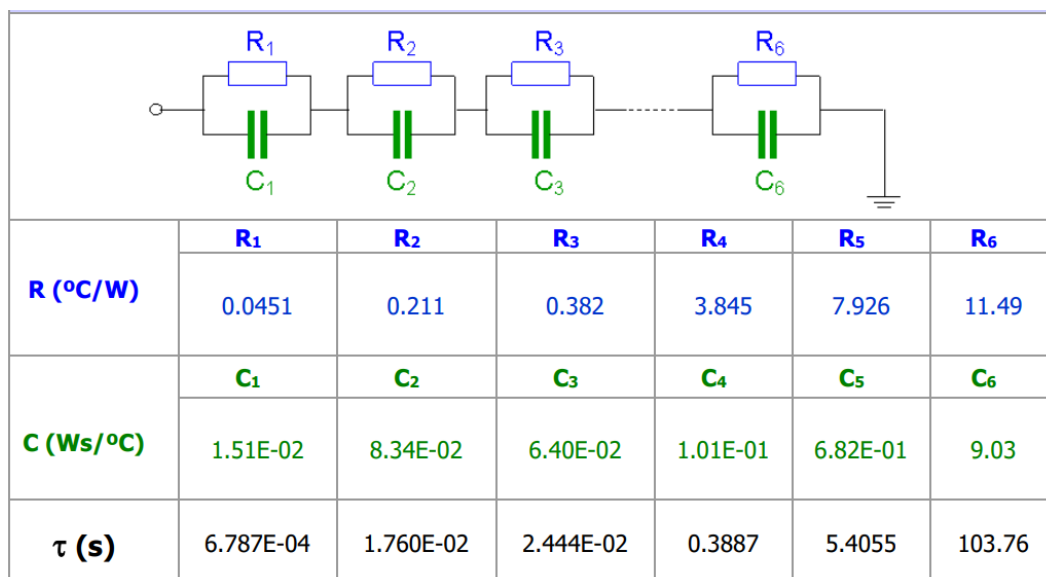
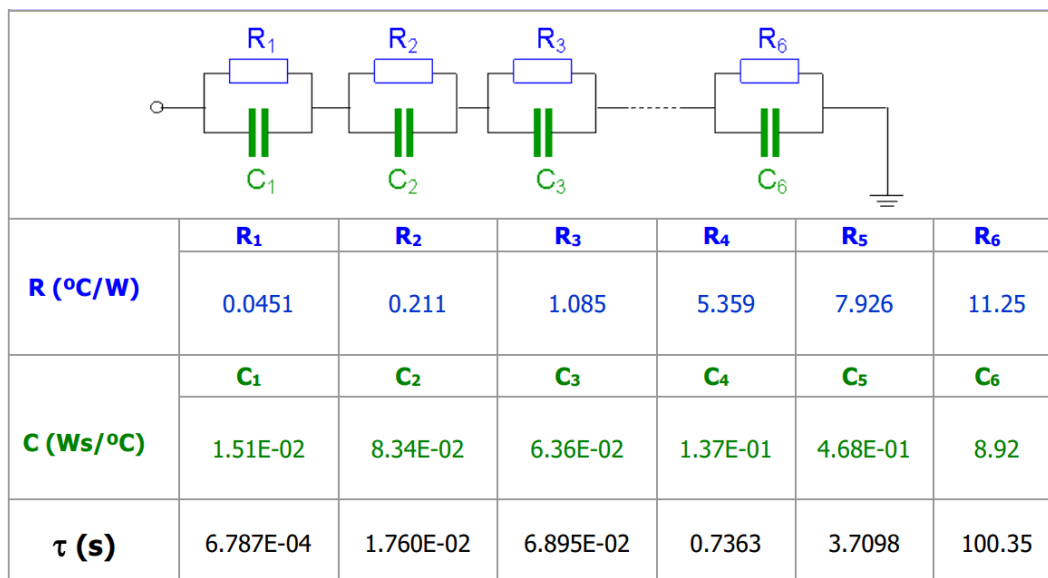


Figure 20. IPS1025HQ/HQ-32/HFQ thermal model on 2s2p Jedec board


7 Max operating frequency

All electronic switches have a limit in terms of maximum operating frequency due to the switching losses and consequent device overheating, causing the thermal protection intervention.

The following figures summarize the maximum operating frequency versus the ambient temperature in the case of IPS1025H/HQ (I_{out}=2.4 A) and IPS1025H-32/HQ-32 (I_{out}=5.0 A).

The values are referred to a resistive load and input signal duty cycle of 50%.

Figure 21. IPS1025H and IPS1025HQ max. operating frequency vs. T_{AMB}

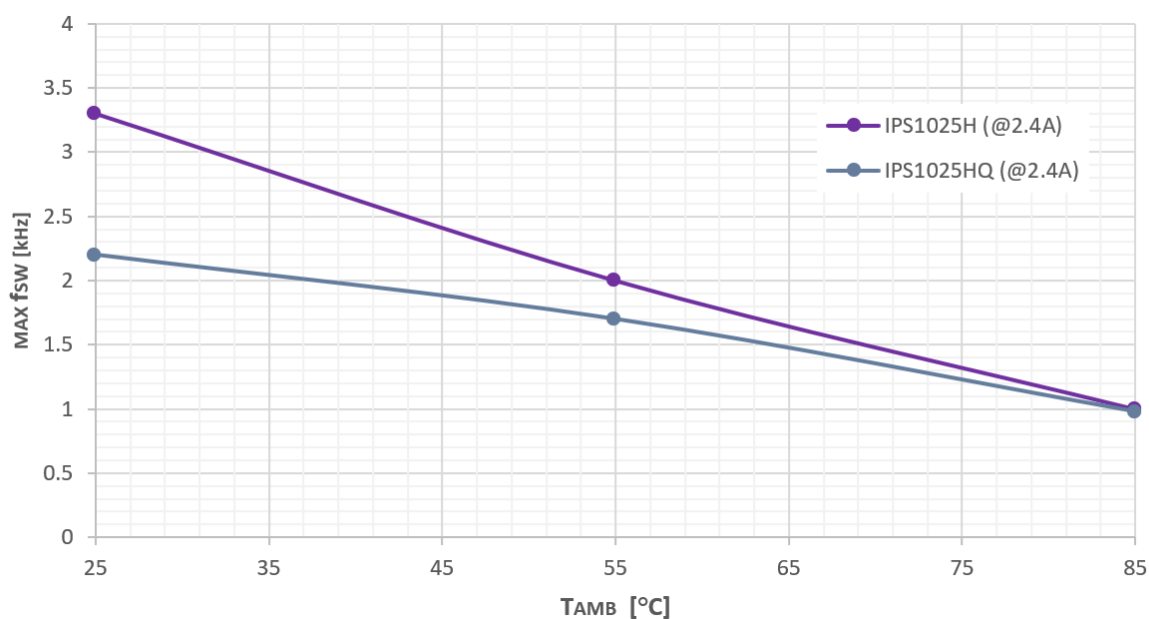
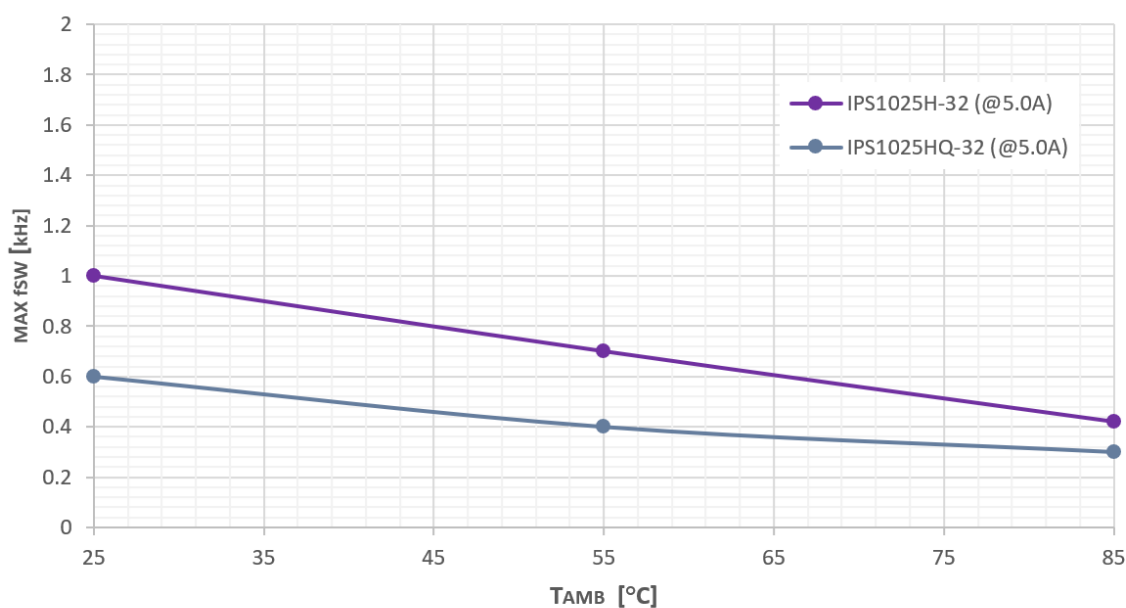


Figure 22. IPS1025H-32 and IPS1025HQ-32 max. operating frequency vs. T_{AMB}



8 Summary

In this document, we introduced ST's new generation of Intelligent Power Switches, IPS1025H, IPS1025HF and IPS1025H-32 (in PowerSSO24 package), and IPS1025HQ, IPS1025HFQ and IPS1025HQ-32 (in QFN48L 8x6 mm package), featuring an active inrush current control mechanism called Smart Load Management.

We outlined a common technical challenge in industrial digital I/O systems and proposed how it can be effectively solved with the new IPS. After a brief overview of the main IC parameters, we explained how it can be configured to one of three available operation modes and which are the datasheet parameters corresponding to each operation mode.

We demonstrated the effect of different configurations on a practical example using a filament lamp as a model of electrical load with inrush current.

In the section 5 we specify the differences in terms of electrical parameters of IPS1025HF/HFQ respect the IPS1025H/HQ and underline the usefulness of these parameters in the safety applications.

Section 6 is dedicated to the effects of different packages (PowerSSO24 and QFN48L) on the IC's thermal performances. The thermal resistances $R_{TH(JA)}$ and related thermal models are reported.

The last section shows the maximum operating frequencies versus the ambient temperature for the different devices of the IPS1025 family.

The IPS1025H/HQ, IPS1025HF/HFQ and IPS1025H-32/HQ-32 ICs were developed from many years of experience with industrial digital I/O design in mind, resulting in chips that are a perfect fit for long-lasting, reliable operation in the most challenging industrial applications.

Revision history

Table 4. Document revision history

Date	Version	Changes
09-Sep-2022	1	Initial release.
15-Jul-2024	2	Added Section 6 and Section 7 ; some minor changes.
14-Oct-2024	3	Added Figure 19 and Figure 20 ; some minor changes.

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